

ON SEMICONDUCTOR TIN WHISKER REPORT ON semiconductor Philippines Assembly Site, Matte Tin over Copper

Introduction

This report is for an evaluation being conducted to measure tin whisker growth on a copper leadframe package assembled at ON Semiconductor's Carmona, Philippines assembly site. The results of this evaluation are applicable to all Cu based leadframe packages at this assembly site.

Package type: SOIC8 Leadframe material: Cu

Plating: Matte tin

Anneal: 1 hour at 150°C within 24 hours of plating

Test Conditions/Procedure

Three test conditions are being used, per JEDEC standard JESD201: Temp Cycle (-55/85°C) for 3000 cycles (inspections at 500 cycle intervals) Storage at 55°C/85%RH for 4000 hours (inspections at 1000 hour intervals) Storage at 30°C/60%RH for 4000 hours (inspections at 1000 hour intervals)

Testing is being conducted on units with three different preconditioning treatments:

- 1. no preconditioning
- 2. units preconditioned with a SnPn reflow profile (peak temp 220°C)
- 3. units preconditioned with a Pb-free reflow profile (peak temp 260°C).

Samples were taken from three separate assembly lots. Three units per lot, three leads per sample, and five areas per lead are inspected by SEM at each inspection point.

Results

The maximum whisker length observed for each unit was noted and compared to the acceptance criteria listed in JESD201 for Class 2 products (40μ maximum for the storage tests and 45μ maximum for temperature cycle).



WHISKER INSPECTION RESULTS			
Precon.	30°C/60%RH (hours) 1000 2000 3000 4000	55°C/85%RH (hours) 1000 2000 3000 4000	Temp Cycles 500 1000 1500 2000 2500 3000
None	Pass Pass Pass Pass	Pass Pass Pass Pass	Pass Pass Pass Pass Pass
SnPb	Pass Pass Pass Pass	Pass Pass Pass Pass	Pass Pass Pass Pass Pass
Pb-free	Pass Pass Pass Pass	Pass Pass Pass Pass	Pass Pass Pass Pass Pass

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